

300mm Fully-Automatic BG Tape Laminator

RAD-3520F/12



Outline

- High precision fully-automatic tape laminator.
- We have now improved the performance of the top-selling model "RAD-3510F/12" and have developed the "RAD-3520F/12," which offers better performance and a smaller footprint.
- Performs non-contact alignment and tape lamination using a tape tension control function, as well as wafer handling and tape cutting using a multi-joint robot arm.
- Improves the wafer processing volume per roll of tape a maximum of 16%
*When the tape is a 100m roll and the wafer size is 300mm (12 inch) in diameter
- FOUP opener with wafer mapping function is available as standard feature

Options

- Various cleaning functions
- Automatic cutter exchange function
- ESD (Electro-Static Discharge) countermeasures etc

Facility

Power Supply	Voltage	: AC200-230V ± 10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power Consumption	: 3.0kW
Air supply	Air Pressure	: 0.6 ~0.8MPa
	Air Consumption	: Less than 300L(ANR)

Applicable Wafer Size

200mm, 300mm
Please inquire about options for compatibility with specific wafer sizes.

Size

Width : 1,245mm
Depth : 1,850mm
Height : 1,920mm
(Excluding the signal tower)

Weight

1,250kg

UPH

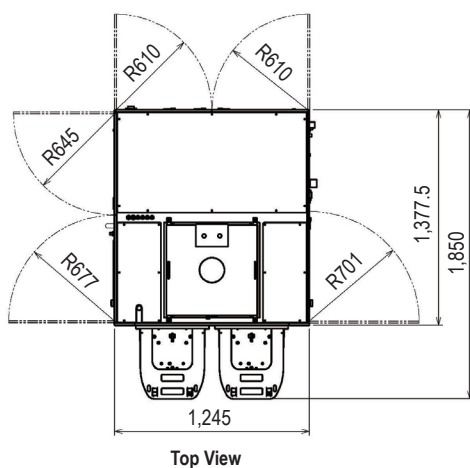
70 wafers/hour
100 wafers/hour (High-speed spec option)

The above processing capacity is based on following conditions

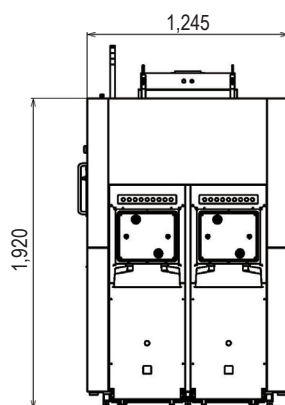
Wafer : 300mm diameter non-polished mirror wafer
Back grinding tape : Adwill P-4140A

Suitable Tapes •Back grinding tape 「Adwill E series」,
「Adwill P series」,

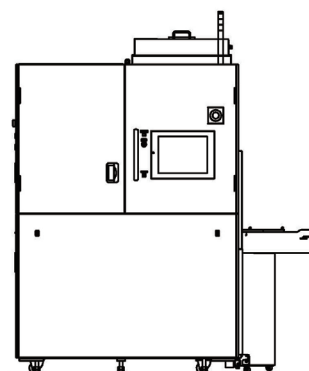
External View



Top View



Front View



Left Side View

Unit mm



LINTEC Corporation Linking your dreams

● Head Office: 23-23 Honcho, Itabashi-ku, Tokyo 173-0001, Japan

Contact: Advanced Materials Operations 8th Fl., Bunkyo Garden Gate Tower, 1-1-1 Koishikawa,
Bunkyo-ku, Tokyo 112-0002, Japan
TEL. +81-3-3868-7737 FAX. +81-3-3868-7726

<https://www.adwill-global.com/en>